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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I ² C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	27
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 16x10b Slope, 16x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-UFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4125lqi-s422

PSoC® 4: PSoC 4100S Family Datasheet



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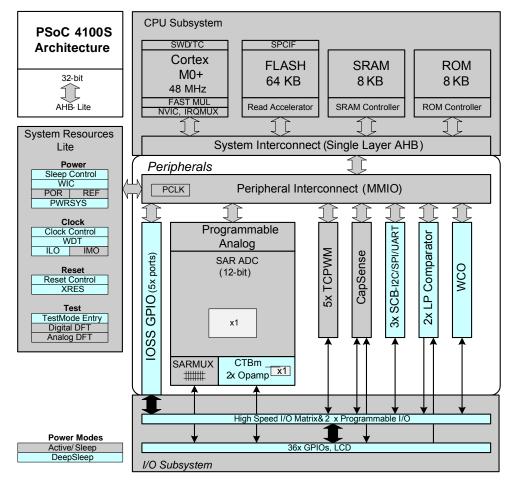


Figure 1. Block Diagram

PSoC 4100S devices include extensive support for programming, testing, debugging, and tracing both hardware and firmware.

The ARM Serial-Wire Debug (SWD) interface supports all programming and debug features of the device.

Complete debug-on-chip functionality enables full-device debugging in the final system using the standard production device. It does not require special interfaces, debugging pods, simulators, or emulators. Only the standard programming connections are required to fully support debug.

The PSoC Creator IDE provides fully integrated programming and debug support for the PSoC 4100S devices. The SWD interface is fully compatible with industry-standard third-party tools. The PSoC 4100S family provides a level of security not possible with multi-chip application solutions or with microcontrollers. It has the following advantages:

- Allows disabling of debug features
- Robust flash protection
- Allows customer-proprietary functionality to be implemented in on-chip programmable blocks

The debug circuits are enabled by default and can be disabled in firmware. If they are not enabled, the only way to re-enable them is to erase the entire device, clear flash protection, and reprogram the device with new firmware that enables debugging. Thus firmware control of debugging cannot be over-ridden without erasing the firmware thus providing security.

Additionally, all device interfaces can be permanently disabled (device security) for applications concerned about phishing attacks due to a maliciously reprogrammed device or attempts to defeat security by starting and interrupting flash programming sequences. All programming, debug, and test interfaces are disabled when maximum device security is enabled. Therefore, PSoC 4100S, with device security enabled, may not be returned for failure analysis. This is a trade-off the PSoC 4100S allows the customer to make.



Reset

The PSoC 4100S can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset by asserting it active low. The XRES pin has an internal pull-up resistor that is always enabled.

Analog Blocks

12-bit SAR ADC

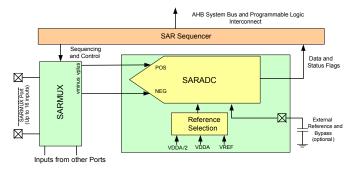
The 12-bit, 1-Msps SAR ADC can operate at a maximum clock rate of 18 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The Sample-and-Hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. It is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) with zero switching overhead (that is, aggregate sampling bandwidth is equal to 1 Msps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is not available in Deep Sleep mode as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 V to 5.5 V.

Figure 3. SAR ADC



Two Opamps (Continuous-Time Block; CTB)

The PSoC 4100S has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, Voltage

Buffers, Filters, Trans-Impedance Amplifiers, and other functions can be realized, in some cases with external passives. saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the Sample-and-Hold circuit of the ADC without requiring external buffering.

Low-power Comparators (LPC)

The PSoC 4100S has a pair of low-power comparators, which can also operate in Deep Sleep modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode where the system wake-up circuit is activated by a comparator switch event. The LPC outputs can be routed to pins.

Current DACs

The PSoC 4100S has two IDACs, which can drive any of the pins on the chip. These IDACs have programmable current ranges.

Analog Multiplexed Buses

The PSoC 4100S has two concentric independent buses that go around the periphery of the chip. These buses (called amux buses) are connected to firmware-programmable analog switches that allow the chip's internal resources (IDACs, comparator) to connect to any pin on the I/O Ports.

Programmable Digital Blocks

The Programmable I/O (Smart I/O) block is a fabric of switches and LUTs that allows Boolean functions to be performed in signals being routed to the pins of a GPIO port. The Smart I/O can perform logical operations on input pins to the chip and on signals going out as outputs.

Fixed Function Digital

Timer/Counter/PWM (TCPWM) Block

The TCPWM block consists of a 16-bit counter with user-programmable period length. There is a capture register to record the count value at the time of an event (which may be an I/O event), a period register that is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals that are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as dead-band programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an over-current state is indicated and the PWM driving the FETs needs to be shut off immediately with no time for software intervention. There are five TCPWM blocks in the PSoC 4100S.

Serial Communication Block (SCB)

The PSoC 4100S has three serial communication blocks, which can be programmed to have SPI, I2C, or UART functionality.

I²C Mode: The hardware I²C block implements a full multi-master and slave interface (it is capable of multi-master arbitration). This block is capable of operating at speeds of up to 400 kbps (Fast Mode) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. It also



supports EZI2C that creates a mailbox address range in the memory of the PSoC 4100S and effectively reduces I²C communication to reading from and writing to an array in memory. In addition, the block supports an 8-deep FIFO for receive and transmit which, by increasing the time given for the CPU to read data, greatly reduces the need for clock stretching caused by the CPU not having read data on time.

The I^2C peripheral is compatible with the I^2C Standard-mode and Fast-mode devices as defined in the NXP I^2C -bus specification and user manual (UM10204). The I^2C bus I/O is implemented with GPIO in open-drain modes.

The PSoC 4100S is not completely compliant with the I²C spec in the following respect:

■ GPIO cells are not overvoltage tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I²C system.

UART Mode: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

SPI Mode: The SPI mode supports full Motorola SPI, TI SSP (adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.

GPIO

The PSoC 4100S has up to 36 GPIOs. The GPIO block implements the following:

- Eight drive modes:
 - ☐ Analog input mode (input and output buffers disabled)
 - □ Input only
 - ☐ Weak pull-up with strong pull-down
 - □ Strong pull-up with weak pull-down
 - □ Open drain with strong pull-down
 - □ Open drain with strong pull-up
 - $\ensuremath{\square}$ Strong pull-up with strong pull-down
 - □ Weak pull-up with weak pull-down
- Input threshold select (CMOS or LVTTL).
- Individual control of input and output buffer enabling/disabling in addition to the drive strength modes
- Selectable slew rates for dV/dt related noise control to improve EMI

The pins are organized in logical entities called ports, which are 8-bit in width (less for Ports 2 and 3). During power-on and reset, the blocks are forced to the disable state so as not to crowbar any inputs and/or cause excess turn-on current. A multiplexing network known as a high-speed I/O matrix is used to multiplex between various signals that may connect to an I/O pin.

Data output and pin state registers store, respectively, the values to be driven on the pins and the states of the pins themselves.

Every I/O pin can generate an interrupt if so enabled and each I/O port has an interrupt request (IRQ) and interrupt service routine (ISR) vector associated with it (5 for PSoC 4100S).

Special Function Peripherals

CapSense

CapSense is supported in the PSoC 4100S through a CapSense Sigma-Delta (CSD) block that can be connected to any pins through an analog multiplex bus via analog switches. CapSense function can thus be provided on any available pin or group of pins in a system under software control. A PSoC Creator component is provided for the CapSense block to make it easy for the user.

Shield voltage can be driven on another analog multiplex bus to provide water-tolerance capability. Water tolerance is provided by driving the shield electrode in phase with the sense electrode to keep the shield capacitance from attenuating the sensed input. Proximity sensing can also be implemented.

The CapSense block has two IDACs, which can be used for general purposes if CapSense is not being used (both IDACs are available in that case) or if CapSense is used without water tolerance (one IDAC is available).

The CapSense block also provides a 10-bit Slope ADC function which can be used in conjunction with the CapSense function.

The CapSense block is an advanced, low-noise, programmable block with programmable voltage references and current source ranges for improved sensitivity and flexibility. It can also use an external reference voltage. It has a full-wave CSD mode that alternates sensing to VDDA and ground to null out power-supply related noise.

LCD Segment Drive

The PSoC 4100S has an LCD controller, which can drive up to 4 commons and up to 32 segments. It uses full digital methods to drive the LCD segments requiring no generation of internal LCD voltages. The two methods used are referred to as Digital Correlation and PWM. Digital Correlation pertains to modulating the frequency and drive levels of the common and segment signals to generate the highest RMS voltage across a segment to light it up or to keep the RMS signal to zero. This method is good for STN displays but may result in reduced contrast with TN (cheaper) displays. PWM pertains to driving the panel with PWM signals to effectively use the capacitance of the panel to provide the integration of the modulated pulse-width to generate the desired LCD voltage. This method results in higher power consumption but can result in better results when driving TN displays. LCD operation is supported during Deep Sleep refreshing a small display buffer (4 bits; 1 32-bit register per port).



Pinouts

The following table provides the pin list for PSoC 4100S for the 48-pin TQFP, 44-pin TQFP, 40-pin QFN, 32-pin QFN, and 35-ball CSP packages. All port pins support GPIO.

Table 1. Pin List

48-1	TQFP	44-	TQFP	40	-QFN	32	-QFN	35-CSP		
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name	
28	P0.0	24	P0.0	22	P0.0	17	P0.0	C3	P0.0	
29	P0.1	25	P0.1	23	P0.1	18	P0.1	A5	P0.1	
30	P0.2	26	P0.2	24	P0.2	19	P0.2	A4	P0.2	
31	P0.3	27	P0.3	25	P0.3	20	P0.3	A3	P0.3	
32	P0.4	28	P0.4	26	P0.4	21	P0.4	В3	P0.4	
33	P0.5	29	P0.5	27	P0.5	22	P0.5	A6	P0.5	
34	P0.6	30	P0.6	28	P0.6	23	P0.6	B4	P0.6	
35	P0.7	31	P0.7	29	P0.7			B5	P0.7	
36	XRES	32	XRES	30	XRES	24	XRES	В6	XRES	
37	VCCD	33	VCCD	31	VCCD	25	VCCD	A7	VCCD	
38	VSSD			DN	VSSD	26	VSSD	В7	VSS	
39	VDDD	34	VDDD	32	VDDD			C7	VDD	
40	VDDA	35	VDDA	33	VDDA	27	VDD	C7	VDD	
41	VSSA	36	VSSA	34	VSSA	28	VSSA	В7	VSS	
42	P1.0	37	P1.0	35	P1.0	29	P1.0	C4	P1.0	
43	P1.1	38	P1.1	36	P1.1	30	P1.1	C5	P1.1	
44	P1.2	39	P1.2	37	P1.2	31	P1.2	C6	P1.2	
45	P1.3	40	P1.3	38	P1.3	32	P1.3	D7	P1.3	
46	P1.4	41	P1.4	39	P1.4			D4	P1.4	
47	P1.5	42	P1.5					D5	P1.5	
48	P1.6	43	P1.6					D6	P1.6	
1	P1.7/VREF	44	P1.7/VREF	40	P1.7/VREF	1	P1.7/VREF	E7	P1.7/VRE	
		1	VSSD							
2	P2.0	2	P2.0	1	P2.0	2	P2.0			
3	P2.1	3	P2.1	2	P2.1	3	P2.1			
4	P2.2	4	P2.2	3	P2.2	4	P2.2	D3	P2.2	
5	P2.3	5	P2.3	4	P2.3	5	P2.3	E4	P2.3	
6	P2.4	6	P2.4	5	P2.4			E5	P2.4	
7	P2.5	7	P2.5	6	P2.5	6	P2.5	E6	P2.5	
8	P2.6	8	P2.6	7	P2.6	7	P2.6	E3	P2.6	
9	P2.7	9	P2.7	8	P2.7	8	P2.7	E2	P2.7	
10	VSSD	10	VSSD	9	VSSD		1			
12	P3.0	11	P3.0	10	P3.0	9	P3.0	E1	P3.0	
13	P3.1	12	P3.1	11	P3.1	10	P3.1	D2	P3.1	
14	P3.2	13	P3.2	12	P3.2	11	P3.2	D1	P3.2	
16	P3.3	14	P3.3	13	P3.3	12	P3.3	C1	P3.3	
17	P3.4	15	P3.4	14	P3.4			C2	P3.4	
18	P3.5	16	P3.5	15	P3.5					

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Alternate Pin Functions

Each Port pin has can be assigned to one of multiple functions; it can, for instance, be an analog I/O, a digital peripheral function, an LCD pin, or a CapSense pin. The pin assignments are shown in the following table.

Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P0.0	lpcomp.in_p[0]				tcpwm.tr_in[0]	scb[2].i2c_scl:0	scb[0].spi_select1:0
P0.1	lpcomp.in_n[0]				tcpwm.tr_in[1]	scb[2].i2c_sda:0	scb[0].spi_select2:0
P0.2	lpcomp.in_p[1]						scb[0].spi_select3:0
P0.3	lpcomp.in_n[1]						scb[2].spi_select0
P0.4	wco.wco_in			scb[1].uart_rx:0	scb[2].uart_rx:0	scb[1].i2c_scl:0	scb[1].spi_mosi:1
P0.5	wco.wco_out			scb[1].uart_tx:0	scb[2].uart_tx:0	scb[1].i2c_sda:0	scb[1].spi_miso:1
P0.6			srss.ext_clk	scb[1].uart_cts:0	scb[2].uart_tx:1		scb[1].spi_clk:1
P0.7			tcpwm.line[0]:2	scb[1].uart_rts:0			scb[1].spi_select0:1
P1.0	ctb0_oa0+		tcpwm.line[2]:1	scb[0].uart_rx:1		scb[0].i2c_scl:0	scb[0].spi_mosi:1
P1.1	ctb0_oa0-		tcpwm.line_compl[2]:1	scb[0].uart_tx:1		scb[0].i2c_sda:0	scb[0].spi_miso:1
P1.2	ctb0_oa0_out		tcpwm.line[3]:1	scb[0].uart_cts:1	tcpwm.tr_in[2]	scb[2].i2c_scl:1	scb[0].spi_clk:1
P1.3	ctb0_oa1_out		tcpwm.line_compl[3]:1	scb[0].uart_rts:1	tcpwm.tr_in[3]	scb[2].i2c_sda:1	scb[0].spi_select0:1
P1.4	ctb0_oa1-						scb[0].spi_select1:1
P1.5	ctb0_oa1+						scb[0].spi_select2:1
P1.6	ctb0_oa0+						scb[0].spi_select3:1
P1.7	ctb0_oa1+ sar_ext_vref0 sar_ext_vref1						scb[2].spi_clk
P2.0	sarmux[0]	prgio[0].io[0]	tcpwm.line[4]:0	csd.comp	tcpwm.tr_in[4]	scb[1].i2c_scl:1	scb[1].spi_mosi:2
P2.1	sarmux[1]	prgio[0].io[1]	tcpwm.line_compl[4]:0		tcpwm.tr_in[5]	scb[1].i2c_sda:1	scb[1].spi_miso:2
P2.2	sarmux[2]	prgio[0].io[2]					scb[1].spi_clk:2
P2.3	sarmux[3]	prgio[0].io[3]					scb[1].spi_select0:2

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Port/Pin	Analog	Smart I/O	Alternate Function 1	Alternate Function 2	Alternate Function 3	Deep Sleep 1	Deep Sleep 2
P2.4	sarmux[4]	prgio[0].io[4]	tcpwm.line[0]:1				scb[1].spi_select1:1
P2.5	sarmux[5]	prgio[0].io[5]	tcpwm.line_compl[0]:1				scb[1].spi_select2:1
P2.6	sarmux[6]	prgio[0].io[6]	tcpwm.line[1]:1				scb[1].spi_select3:1
P2.7	sarmux[7]	prgio[0].io[7]	tcpwm.line_compl[1]:1			lpcomp.comp[0]:1	scb[2].spi_mosi
P3.0		prgio[1].io[0]	tcpwm.line[0]:0	scb[1].uart_rx:1		scb[1].i2c_scl:2	scb[1].spi_mosi:0
P3.1		prgio[1].io[1]	tcpwm.line_compl[0]:0	scb[1].uart_tx:1		scb[1].i2c_sda:2	scb[1].spi_miso:0
P3.2		prgio[1].io[2]	tcpwm.line[1]:0	scb[1].uart_cts:1		cpuss.swd_data	scb[1].spi_clk:0
P3.3		prgio[1].io[3]	tcpwm.line_compl[1]:0	scb[1].uart_rts:1		cpuss.swd_clk	scb[1].spi_select0:0
P3.4		prgio[1].io[4]	tcpwm.line[2]:0		tcpwm.tr_in[6]		scb[1].spi_select1:0
P3.5		prgio[1].io[5]	tcpwm.line_compl[2]:0				scb[1].spi_select2:0
P3.6		prgio[1].io[6]	tcpwm.line[3]:0				scb[1].spi_select3:0
P3.7		prgio[1].io[7]	tcpwm.line_compl[3]:0			lpcomp.comp[1]:1	scb[2].spi_miso
P4.0	csd.vref_ext			scb[0].uart_rx:0		scb[0].i2c_scl:1	scb[0].spi_mosi:0
P4.1	csd.cshieldpads			scb[0].uart_tx:0		scb[0].i2c_sda:1	scb[0].spi_miso:0
P4.2	csd.cmodpad			scb[0].uart_cts:0		lpcomp.comp[0]:0	scb[0].spi_clk:0
P4.3	csd.csh_tank			scb[0].uart_rts:0		lpcomp.comp[1]:0	scb[0].spi_select0:0

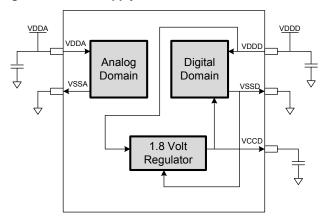
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Power

The following power system diagram shows the set of power supply pins as implemented for the PSoC 4100S. The system has one regulator in Active mode for the digital circuitry. There is no analog regulator; the analog circuits run directly from the V_{DD} input.

Figure 4. Power Supply Connections



There are two distinct modes of operation. In Mode 1, the supply voltage range is 1.8 V to 5.5 V (unregulated externally; internal regulator operational). In Mode 2, the supply range is 1.8 V ±5% (externally regulated; 1.71 to 1.89, internal regulator bypassed).

Mode 1: 1.8 V to 5.5 V External Supply

In this mode, the PSoC 4100S is powered by an external power supply that can be anywhere in the range of 1.8 to 5.5 V. This range is also designed for battery-powered operation. For example, the chip can be powered from a battery system that starts at 3.5 V and works down to 1.8 V. In this mode, the internal regulator of the PSoC 4100S supplies the internal logic and its output is connected to the $V_{\rm CCD}$ pin. The VCCD pin must be bypassed to ground via an external capacitor (0.1 μ F; X5R ceramic or better) and must not be connected to anything else.

Mode 2: 1.8 V ±5% External Supply

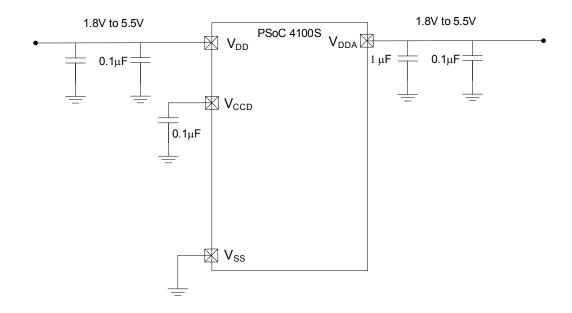
In this mode, the PSoC 4100S is powered by an external power supply that must be within the range of 1.71 to 1.89 V; note that this range needs to include the power supply ripple too. In this mode, the VDD and VCCD pins are shorted together and bypassed. The internal regulator can be disabled in the firmware.

Bypass capacitors must be used from VDDD to ground. The typical practice for systems in this frequency range is to use a capacitor in the 1- μ F range, in parallel with a smaller capacitor (0.1 μ F, for example). Note that these are simply rules of thumb and that, for critical applications, the PCB layout, lead inductance, and the bypass capacitor parasitic should be simulated to design and obtain optimal bypassing.

An example of a bypass scheme is shown in the following diagram.

Figure 5. External Supply Range from 1.8 V to 5.5 V with Internal Regulator Active

Power supply bypass connections example



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Development Support

The PSoC 4100S family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit www.cypress.com/go/psoc4 to find out more.

Documentation

A suite of documentation supports the PSoC 4100S family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

Software User Guide: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

Component Datasheets: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

Application Notes: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

Technical Reference Manual: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers. The TRM is available in the Documentation section at www.cypress.com/psoc4.

Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

Tools

With industry standard cores, programming, and debugging interfaces, the PSoC 4100S family is part of a development tool ecosystem. Visit us at www.cypress.com/go/psoccreator for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.



Electrical Specifications

Absolute Maximum Ratings

Table 2. Absolute Maximum Ratings^[1]

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID1	V _{DDD_ABS}	Digital supply relative to V _{SS}	-0.5	_	6		_
SID2	V _{CCD_ABS}	Direct digital core voltage input relative to V _{SS}	-0.5	-	1.95	V	_
SID3	V _{GPIO_ABS}	GPIO voltage	-0.5	-	V _{DD} +0.5		_
SID4	I _{GPIO_ABS}	Maximum current per GPIO	-25	-	25		_
SID5	GPIO_injection	GPIO injection current, Max for $V_{IH} > V_{DDD}$, and Min for $V_{IL} < V_{SS}$	-0.5	-	0.5	mA	Current injected per pin
BID44	ESD_HBM	Electrostatic discharge human body model	2200	_	_	V	-
BID45	ESD_CDM	Electrostatic discharge charged device model	500	-	_	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	-
BID46	LU	Pin current for latch-up	-140	-	140	mA	_

Device Level Specifications

All specifications are valid for $-40~^{\circ}\text{C} \le T_A \le 85~^{\circ}\text{C}$ and $T_J \le 100~^{\circ}\text{C}$, except where noted. Specifications are valid for 1.71 V to 5.5 V, except where noted.

Table 3. DC Specifications

Typical values measured at V_{DD} = 3.3 V and 25 °C.

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID53	V_{DD}	Power supply input voltage	1.8	_	5.5		Internally regulated supply
SID255	V_{DD}	Power supply input voltage ($V_{CCD} = V_{DDD} = V_{DDA}$)	1.71	-	1.89	V	Internally unregulated supply
SID54	V_{CCD}	Output voltage (for core logic)	-	1.8	_		_
SID55	C _{EFC}	External regulator voltage bypass	_	0.1	-	μF	X5R ceramic or better
SID56	C _{EXC}	Power supply bypass capacitor	_	1	_	μι	X5R ceramic or better
Active Mode, V	/ _{DD} = 1.8 V to 5	.5 V. Typical values measured at VDD	= 3.3 V an	d 25 °C.			
SID10	I _{DD5}	Execute from flash; CPU at 6 MHz	-	1.8	2.7		Max is at 85 °C and 5.5 V
SID16	I _{DD8}	Execute from flash; CPU at 24 MHz	-	3.0	4.75	mA	Max is at 85 °C and 5.5 V
SID19	I _{DD11}	Execute from flash; CPU at 48 MHz	_	5.4	6.85		Max is at 85 °C and 5.5 V

Note

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^{1.} Usage above the absolute maximum conditions listed in Table 2 may cause permanent damage to the device. Exposure to Absolute Maximum conditions for extended periods of time may affect device reliability. The Maximum Storage Temperature is 150 °C in compliance with JEDEC Standard JESD22-A103, High Temperature Storage Life. When used below Absolute Maximum conditions but above normal operating conditions, the device may not operate to specification.



Table 9. CTBm Opamp Specifications (continued)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID299	T_OP_WAKE	From disable to enable, no external RC dominating	_	_	25	μs	_
SID299A	OL_GAIN	Open Loop Gain	_	90	-	dB	
	COMP_MODE	Comparator mode; 50 mV drive, T _{rise} =T _{fall} (approx.)					
SID300	TPD1	Response time; power=hi	_	150	_		Input is 0.2 V to V _{DDA} -0.2 V
SID301	TPD2	Response time; power=med	-	500	_	ns	Input is 0.2 V to V _{DDA} -0.2 V
SID302	TPD3	Response time; power=lo	_	2500	_		Input is 0.2 V to V _{DDA} -0.2 V
SID303	VHYST_OP	Hysteresis	_	10	_	mV	_
SID304	WUP_CTB	Wake-up time from Enabled to Usable	_	-	25	μs	-
	Deep Sleep Mode	Mode 2 is lowest current range. Mode 1 has higher GBW.					
SID_DS_1	I _{DD_HI_M1}	Mode 1, High current	_	1400	_		25 °C
SID_DS_2	I _{DD_MED_M1}	Mode 1, Medium current	_	700	-		25 °C
SID_DS_3	I _{DD_LOW_M1}	Mode 1, Low current	_	200	-		25 °C
SID_DS_4	I _{DD_HI_M2}	Mode 2, High current	-	120	_	μA	25 °C
SID_DS_5	I _{DD_MED_M2}	Mode 2, Medium current	_	60	_		25 °C
SID_DS_6	I _{DD_LOW_M2}	Mode 2, Low current	_	15	_		25 °C

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CSD

Table 14. CSD and IDAC Specifications

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SYS.PER#3	VDD_RIPPLE	Max allowed ripple on power supply, DC to 10 MHz	ı	_	±50	mV	V _{DD} > 2 V (with ripple), 25 °C T _A , Sensitivity = 0.1 pF
SYS.PER#16	VDD_RIPPLE_1.8	Max allowed ripple on power supply, DC to 10 MHz	-	_	±25	mV	V_{DD} > 1.75V (with ripple), 25 °C T _A , Parasitic Capacitance (C _P) < 20 pF, Sensitivity ≥ 0.4 pF
SID.CSD.BLK	ICSD	Maximum block current	-	-	4000	μA	Maximum block current for both IDACs in dynamic (switching) mode including comparators, buffer, and reference generator.
SID.CSD#15	V _{REF}	Voltage reference for CSD and Comparator	0.6	1.2	V _{DDA} - 0.6	V	V _{DDA} - 0.06 or 4.4, whichever is lower
SID.CSD#15A	VREF_EXT	External Voltage reference for CSD and Comparator	0.6		V _{DDA} - 0.6	V	V _{DDA} - 0.06 or 4.4, whichever is lower
SID.CSD#16	IDAC1IDD	IDAC1 (7-bits) block current	_	-	1750	μΑ	
SID.CSD#17	IDAC2IDD	IDAC2 (7-bits) block current	_	-	1750	μΑ	
SID308	VCSD	Voltage range of operation	1.71	-	5.5	V	1.8 V ±5% or 1.8 V to 5.5 \
SID308A	VCOMPIDAC	Voltage compliance range of IDAC	0.6	-	V _{DDA} -0.6	V	V _{DDA} - 0.06 or 4.4, whichever is lower
SID309	IDAC1DNL	DNL	-1	-	1	LSB	
SID310	IDAC1INL	INL	-2	_	2	LSB	INL is ± 5.5 LSB for $V_{DDA} < 2$ V
SID311	IDAC2DNL	DNL	-1	-	1	LSB	
SID312	IDAC2INL	INL	-2	_	2	LSB	INL is ± 5.5 LSB for $V_{DDA} < 2$ V
SID313	SNR	Ratio of counts of finger to noise. Guaranteed by characterization	5	_	_	Ratio	Capacitance range of 5 to 35 pF, 0.1-pF sensitivity. All use cases. V _{DDA} > 2 V.
SID314	IDAC1CRT1	Output current of IDAC1 (7 bits) in low range	4.2	_	5.4	μA	LSB = 37.5-nA typ.
SID314A	IDAC1CRT2	Output current of IDAC1(7 bits) in medium range	34	_	41	μA	LSB = 300-nA typ.
SID314B	IDAC1CRT3	Output current of IDAC1(7 bits) in high range	275	_	330	μA	LSB = 2.4-μA typ.
SID314C	IDAC1CRT12	Output current of IDAC1 (7 bits) in low range, 2X mode	8	-	10.5	μA	LSB = 75-nA typ.
SID314D	IDAC1CRT22	Output current of IDAC1(7 bits) in medium range, 2X mode	69	-	82	μA	LSB = 600-nA typ.
SID314E	IDAC1CRT32	Output current of IDAC1(7 bits) in high range, 2X mode	540	-	660	μA	LSB = 4.8-μA typ.
SID315	IDAC2CRT1	Output current of IDAC2 (7 bits) in low range	4.2	_	5.4	μA	LSB = 37.5-nA typ.
SID315A	IDAC2CRT2	Output current of IDAC2 (7 bits) in medium range	34	_	41	μA	LSB = 300-nA typ.
SID315B	IDAC2CRT3	Output current of IDAC2 (7 bits) in high range	275	_	330	μA	LSB = 2.4-µA typ.
SID315C	IDAC2CRT12	Output current of IDAC2 (7 bits) in low range, 2X mode	8	_	10.5	μA	LSB = 75-nA typ.
SID315D	IDAC2CRT22	Output current of IDAC2(7 bits) in medium range, 2X mode	69	_	82	μA	LSB = 600-nA typ.
SID315E	IDAC2CRT32	Output current of IDAC2(7 bits) in high range, 2X mode	540	_	660	μA	LSB = 4.8-μA typ.
SID315F	IDAC3CRT13	Output current of IDAC in 8-bit mode in low range	8	_	10.5	μA	LSB = 37.5-nA typ.

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Table 14. CSD and IDAC Specifications (continued)

SPEC ID#	Parameter	Description	Min	Тур	Max	Units	Details / Conditions
SID315G	IDAC3CRT23	Output current of IDAC in 8-bit mode in medium range	69	_	82	μA	LSB = 300-nA typ.
SID315H	IDAC3CRT33	Output current of IDAC in 8-bit mode in high range	540	_	660	μA	LSB = 2.4-µA typ.
SID320	IDACOFFSET	All zeroes input	-	_	1	LSB	Polarity set by Source or Sink. Offset is 2 LSBs for 37.5 nA/LSB mode
SID321	IDACGAIN	Full-scale error less offset	-	_	±10	%	
SID322	IDACMISMATCH1	Mismatch between IDAC1 and IDAC2 in Low mode	-	-	9.2	LSB	LSB = 37.5-nA typ.
SID322A	IDACMISMATCH2	Mismatch between IDAC1 and IDAC2 in Medium mode	-	-	5.6	LSB	LSB = 300-nA typ.
SID322B	IDACMISMATCH3	Mismatch between IDAC1 and IDAC2 in High mode	-	-	6.8	LSB	LSB = 2.4-µA typ.
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	-	-	10	μs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	_	-	10	μs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor.	-	2.2	_	nF	5-V rating, X7R or NP0 cap.

Table 15. 10-bit CapSense ADC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SIDA94	A_RES	Resolution	_	_	10	bits	Auto-zeroing is required every millisecond
SIDA95	A_CHNLS_S	Number of channels - single ended	_	-	16		Defined by AMUX Bus.
SIDA97	A-MONO	Monotonicity	_	_	_	Yes	
SIDA98	A_GAINERR	Gain error	-	_	±2	%	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 µF
SIDA99	A_OFFSET	Input offset voltage	-	-	3	mV	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 µF
SIDA100	A_ISAR	Current consumption	_	_	0.25	mΑ	
SIDA101	A_VINS	Input voltage range - single ended	V_{SSA}	_	V_{DDA}	V	
SIDA103	A_INRES	Input resistance	_	2.2	-	ΚΩ	
SIDA104	A_INCAP	Input capacitance	_	20	-	pF	
SIDA106	A_PSRR	Power supply rejection ratio	-	60	_	dB	In V _{REF} (2.4 V) mode with V _{DDA} bypass capacitance of 10 µF
SIDA107	A_TACQ	Sample acquisition time	_	1	-	μs	
SIDA108	A_CONV8	Conversion time for 8-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	_	_	21.3	μs	Does not include acquisition time. Equivalent to 44.8 ksps including acquisition time.
SIDA108A	A_CONV10	Conversion time for 10-bit resolution at conversion rate = Fhclk/(2^(N+2)). Clock frequency = 48 MHz.	_	_	85.3	μs	Does not include acquisition time. Equivalent to 11.6 ksps including acquisition time.

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Table 19. SPI DC Specifications $^{[9]}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID163	ISPI1	Block current consumption at 1 Mbps	-	_	360		_
SID164	ISPI2	Block current consumption at 4 Mbps	-	_	560	μA	_
SID165	ISPI3	Block current consumption at 8 Mbps	_	_	600		-

Table 20. SPI AC Specifications^[8]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions		
SID166	FSPI	SPI Operating frequency (Master; 6X Oversampling)	-	_	8	MHz	SID166		
Fixed SPI	Master Mode A	C Specifications							
SID167	TDMO	MOSI Valid after SClock driving edge	_	_	15		_		
SID168	TDSI	MISO Valid before SClock capturing edge	20	_	_	ns	Full clock, late MISO sampling		
SID169	тнмо	Previous MOSI data hold time	0	_	_		Referred to Slave capturing edge		
Fixed SPI	Slave Mode AC	Specifications							
SID170	TDMI	MOSI Valid before Sclock Capturing edge	40	_	_		-		
SID171	TDSO	MISO Valid after Sclock driving edge	-	_	42 + 3*Tcpu	ns	T _{CPU} = 1/F _{CPU}		
SID171A	TDSO_EXT	MISO Valid after Sclock driving edge in Ext. Clk mode	_	_	48		-		
SID172	THSO	Previous MISO data hold time	0	_	_		_		
SID172A	TSSELSSCK	SSEL Valid to first SCK Valid edge	-	_	100	ns	-		

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Table 21. UART DC Specifications^[9]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID160	I _{UART1}	Block current consumption at 100 Kbps	-	-	55	μΑ	_
SID161	I _{UART2}	Block current consumption at 1000 Kbps	_	_	312	μA	-

Table 22. UART AC Specifications^[9]

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID162	F _{UART}	Bit rate	_	1	1	Mbps	-

Table 23. LCD Direct Drive DC Specifications $^{[9]}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID154	I _{LCDLOW}	Operating current in low power mode	-	5	_	μA	16 × 4 small segment disp. at 50 Hz
SID155	C _{LCDCAP}	LCD capacitance per segment/common driver	-	500	5000	pF	_
SID156	LCD _{OFFSET}	Long-term segment offset	_	20	-	mV	_
SID157	I _{LCDOP1}	LCD system operating current Vbias = 5 V	_	2	_	mA	32 × 4 segments. 50 Hz. 25 °C
SID158	I _{LCDOP2}	LCD system operating current Vbias = 3.3 V		2	1	ША	32 × 4 segments. 50 Hz. 25 °C

Table 24. LCD Direct Drive AC Specifications $^{[9]}$

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID159	F _{LCD}	LCD frame rate	10	50	150	Hz	_

^{9.} Guaranteed by characterization.



SWD Interface

Table 29. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID213	F_SWDCLK1	$3.3 \text{ V} \leq \text{V}_{DD} \leq 5.5 \text{ V}$	ı	1	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71 \text{ V} \le \text{V}_{DD} \le 3.3 \text{ V}$	-	-	7		SWDCLK ≤ 1/3 CPU clock frequency
SID215 ^[12]	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	_	_		-
SID216 ^[12]	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	_	_	ns	-
SID217 ^[12]	T_SWDO_VALID	T = 1/f SWDCLK	_	_	0.5*T	115	-
SID217A ^[12]	T_SWDO_HOLD	T = 1/f SWDCLK	1	_	_		-

Internal Main Oscillator

Table 30. IMO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID218	I _{IMO1}	IMO operating current at 48 MHz	_	_	250	μΑ	_
SID219	I _{IMO2}	IMO operating current at 24 MHz	_	_	180	μΑ	_

Table 31. IMO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID223	F _{IMOTOL1}	Frequency variation at 24, 32, and 48 MHz (trimmed)	1	_	±2	%	
SID226	T _{STARTIMO}	IMO startup time	_	_	7	μs	-
SID228	T _{JITRMSIMO2}	RMS jitter at 24 MHz	-	145	=	ps	_

Internal Low-Speed Oscillator

Table 32. ILO DC Specifications

(Guaranteed by Design)

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID231 ^[12]	I _{ILO1}	ILO operating current	ı	0.3	1.05	μΑ	_

Table 33. ILO AC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID234 ^[12]	T _{STARTILO1}	ILO startup time	-	-	2	ms	_
SID236 ^[12]	T _{ILODUTY}	ILO duty cycle	40	50	60	%	_
SID237	F _{ILOTRIM1}	ILO frequency range	20	40	80	kHz	_

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Note 12. Guaranteed by characterization.



Ordering Information

The marketing part numbers for the PSoC 4100S family are listed in the following table.

								Featur	es							Р	ackag	е	
Category	MPN	Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	Opamp (CTBm)	CSD	10-bit CSD ADC	12-bit SAR ADC	ADC Sample Rate	LP Comparators	TCPWM Blocks	SCB Blocks	Smart I/Os	GPIO	35-WLCSP (0.35mm pitch)	32-QFN	40-QFN	48-TQFP	44-TQFP
	CY8C4124FNI-S403	24	16	4	2	0	1	0		2	5	2	8	31	Х				
	CY8C4124FNI-S413	24	16	4	2	1	1	0		2	5	2	16	31	Χ				
	CY8C4124LQI-S412	24	16	4	2	1	1	0		2	5	2	16	27		Х			
	CY8C4124LQI-S413	24	16	4	2	1	1	0		2	5	2	16	34			Х		
4124	CY8C4124AZI-S413	24	16	4	2	1	1	0		2	5	2	16	36				Х	
	CY8C4124FNI-S433	24	16	4	2	1	1	1	806 ksps	2	5	2	16	31	Х				
	CY8C4124LQI-S432	24	16	4	2	1	1	1	806 ksps	2	5	2	16	27		Х			
	CY8C4124LQI-S433	24	16	4	2	1	1	1	806 ksps	2	5	2	16	34			Х		
	CY8C4124AZI-S433	24	16	4	2	1	1	1	806 ksps	2	5	2	16	36				Х	
	CY8C4125FNI-S423	24	32	4	2	0	1	1	806 ksps	2	5	2	16	31	Х				
	CY8C4125LQI-S422	24	32	4	2	0	1	1	806 ksps	2	5	2	16	27		Х			
	CY8C4125LQI-S423	24	32	4	2	0	1	1	806 ksps	2	5	2	16	34			Х		
	CY8C4125AZI-S423	24	32	4	2	0	1	1	806 ksps	2	5	2	16	36				Х	
	CY8C4125AXI-S423	24	32	4	2	0	1	1	806 ksps	2	5	2	16	36					Х
4125	CY8C4125FNI-S413	24	32	4	2	1	1	0		2	5	2	16	31	Х				
	CY8C4125LQI-S412	24	32	4	2	1	1	0		2	5	2	16	27		Х			
4125	CY8C4125LQI-S413	24	32	4	2	1	1	0		2	5	2	16	34			Х		
	CY8C4125AZI-S413	24	32	4	2	1	1	0		2	5	2	16	36				Х	
	CY8C4125FNI-S433	24	32	4	2	1	1	1	806 ksps	2	5	2	16	31	Х				
	CY8C4125LQI-S432	24	32	4	2	1	1	1	806 ksps	2	5	2	16	27		Х			
	CY8C4125LQI-S433	24	32	4	2	1	1	1	806 ksps	2	5	2	16	34			Х		
	CY8C4125AZI-S433	24	32	4	2	1	1	1	806 ksps	2	5	2	16	36				Х	
	CY8C4125AXI-S433	24	32	4	2	1	1	1	806 ksps	2	5	2	16	36					Х
	CY8C4126AZI-S423	24	64	8	2	0	1	1	806 ksps	2	5	3	16	36				Х	
4126	CY8C4126AXI-S423	24	64	8	2	0	1	1	806 ksps	2	5	3	16	36					Х
4120	CY8C4126AZI-S433	24	64	8	2	1	1	1	806 ksps	2	5	3	16	36				Х	
	CY8C4126AXI-S433	24	64	8	2	1	1	1	806 ksps	2	5	3	16	36					Х
	CY8C4145AZI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36				Х	
4145	CY8C4145AXI-S423	48	32	4	2	0	1	1	1 Msps	2	5	2	16	36					Х
	CY8C4145AXI-S433	48	32	4	2	1	1	1	1 Msps	2	5	2	16	36					Х
_	CY8C4146FNI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	31	Χ				
	CY8C4146LQI-S422	48	64	8	2	0	1	1	1 Msps	2	5	3	16	27		Х			
	CY8C4146LQI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	34			Х		
	CY8C4146AZI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36				Χ	
4146	CY8C4146AXI-S423	48	64	8	2	0	1	1	1 Msps	2	5	3	16	36					Х
7140	CY8C4146FNI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	31	Х				
	CY8C4146LQI-S432	48	64	8	2	1	1	1	1 Msps	2	5	3	16	27		Х			
	CY8C4146LQI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	34			Х		
	CY8C4146AZI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36				Χ	
	CY8C4146AXI-S433	48	64	8	2	1	1	1	1 Msps	2	5	3	16	36					Х



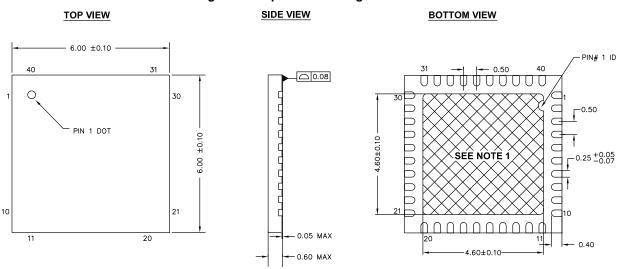


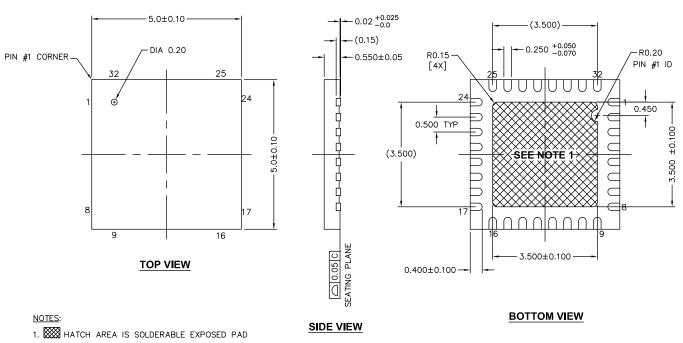
Figure 8. 40-pin QFN Package Outline

NOTES:

- 2. REFERENCE JEDEC # MO-248
- 3. PACKAGE WEIGHT: 68 ±2 mg
- 4. ALL DIMENSIONS ARE IN MILLIMETERS

001-80659 *A

Figure 9. 32-pin QFN Package Outline



- 2. BASED ON REF JEDEC # MO-248
- 3. PACKAGE WEIGHT: 0.0388g
- 4. DIMENSIONS ARE IN MILLIMETERS

001-42168 *E



Acronyms

Table 42. Acronyms Used in this Document

Table 42. Acronyms Used in this Document		
Acronym	Description	
abus	analog local bus	
ADC	analog-to-digital converter	
AG	analog global	
АНВ	AMBA (advanced microcontroller bus architecture) high-performance bus, an ARM data transfer bus	
ALU	arithmetic logic unit	
AMUXBUS	analog multiplexer bus	
API	application programming interface	
APSR	application program status register	
ARM [®]	advanced RISC machine, a CPU architecture	
ATM	automatic thump mode	
BW	bandwidth	
CAN	Controller Area Network, a communications protocol	
CMRR	common-mode rejection ratio	
CPU	central processing unit	
CRC	cyclic redundancy check, an error-checking protocol	
DAC	digital-to-analog converter, see also IDAC, VDAC	
DFB	digital filter block	
DIO	digital input/output, GPIO with only digital capabilities, no analog. See GPIO.	
DMIPS	Dhrystone million instructions per second	
DMA	direct memory access, see also TD	
DNL	differential nonlinearity, see also INL	
DNU	do not use	
DR	port write data registers	
DSI	digital system interconnect	
DWT	data watchpoint and trace	
ECC	error correcting code	
ECO	external crystal oscillator	
EEPROM	electrically erasable programmable read-only memory	
EMI	electromagnetic interference	
EMIF	external memory interface	
EOC	end of conversion	
EOF	end of frame	
EPSR	execution program status register	
ESD	electrostatic discharge	

Table 42. Acronyms Used in this Document (continued)

Acronym	Description
ETM	embedded trace macrocell
FIR	finite impulse response, see also IIR
FPB	flash patch and breakpoint
FS	full-speed
GPIO	general-purpose input/output, applies to a PSoC pin
HVI	high-voltage interrupt, see also LVI, LVD
IC	integrated circuit
IDAC	current DAC, see also DAC, VDAC
IDE	integrated development environment
I ² C, or IIC	Inter-Integrated Circuit, a communications protocol
IIR	infinite impulse response, see also FIR
ILO	internal low-speed oscillator, see also IMO
IMO	internal main oscillator, see also ILO
INL	integral nonlinearity, see also DNL
I/O	input/output, see also GPIO, DIO, SIO, USBIO
IPOR	initial power-on reset
IPSR	interrupt program status register
IRQ	interrupt request
ITM	instrumentation trace macrocell
LCD	liquid crystal display
LIN	Local Interconnect Network, a communications protocol.
LR	link register
LUT	lookup table
LVD	low-voltage detect, see also LVI
LVI	low-voltage interrupt, see also HVI
LVTTL	low-voltage transistor-transistor logic
MAC	multiply-accumulate
MCU	microcontroller unit
MISO	master-in slave-out
NC	no connect
NMI	nonmaskable interrupt
NRZ	non-return-to-zero
NVIC	nested vectored interrupt controller
l	
NVL	nonvolatile latch, see also WOL
NVL opamp	operational amplifier

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